

# **LOW VOLTAGE, 1:18 CLOCK DISTRIBUTION CHIP**

**MPC942C** 

The MPC942 is a 1:18 low voltage clock distribution chip with 2.5V or 3.3V LVCMOS output capabilities. The device is offered in two versions; the MPC942C has an LVCMOS input clock while the MPC942P has a LVPECL input clock. The 18 outputs are 2.5V or 3.3V LVCMOS compatible and feature the drive strength to drive  $50\Omega$  series or parallel terminated transmission lines. With output-to-output skews of 200ps, the MPC942 is ideal as a clock distribution chip for the most demanding of synchronous systems. The 2.5V outputs also make the device ideal for supplying clocks for a high performance Pentium IITM microprocessor based design.

- LVCMOS/LVTTL Clock Input
- 2.5V LVCMOS Outputs for Pentium II Microprocessor Support
- 150ps Maximum Targeted Output-to-Output Skew
- Maximum Output Frequency of 250MHz @ 3.3 V<sub>CC</sub>
- · 32-Lead TQFP Packaging
- Single 3.3V or 2.5V Supply

With a low output impedance ( $\approx$ 12 $\Omega$ ), in both the HIGH and LOW logic states, the output buffers of the MPC942 are ideal for driving series terminated transmission lines. With an output impedance of 12 $\Omega$  the MPC942 can drive two series terminated transmission lines from each output. This capability gives the MPC942 an effective fanout of 1:36. The MPC942 provides enough copies of low skew clocks for most high performance synchronous systems.

The LVCMOS/LVTTL input of the MPC942C provides a more standard LVCMOS interface. The OE pins will place the outputs into a high impedance state. The OE pin has an internal pullup resistor.

The MPC942 is a single supply device. The  $V_{CC}$  power pins require either 2.5V or 3.3V. The 32-lead TQFP package was chosen to optimize performance, board space and cost of the device. The 32-lead TQFP has a 7x7mm body size with a conservative 0.8mm pin spacing.

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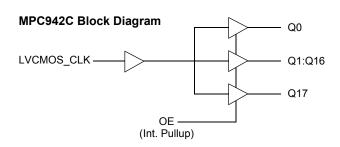
**FA SUFFIX** 32-LEAD TQFP PACKAGE CASE 873A-03



AC SUFFIX
32-LEAD TQFP PACKAGE
Pb-FREE PACKAGE
CASE 873A-03

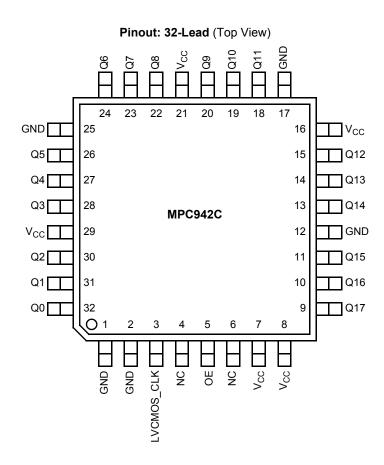
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### **LOGIC DIAGRAM**



### **FUNCTION TABLE**

OE	Output
0	HIGH IMPEDANCE
1	OUTPUTS ENABLED



**Table 1. Absolute Maximum Ratings** 

Symbol	Parameter		Max	Unit
V <sub>CC</sub>	Supply Voltage	-0.3	3.6	V
VI	Input Voltage	-0.3	V <sub>CC</sub> + 0.3	V
I <sub>IN</sub>	Input Current		±20	mA
T <sub>Stor</sub>	Storage Temperature Range	-40	125	°C

Table 2. DC Characteristics ( $T_A$  = 0° to 70°C,  $V_{CCI}$  = 2.5V ±5%,  $V_{CCO}$  = 2.5V ±5%)

Symbol	Characteristic	Min	Тур	Max	Unit	Condition
V <sub>IH</sub>	Input HIGH Voltage	2.0		V <sub>CCI</sub>	V	
V <sub>IL</sub>	Input LOW Voltage			0.8	V	
V <sub>OH</sub>	Output HIGH Voltage	2.0			V	$I_{OH} = -16 \text{ mA}$
V <sub>OL</sub>	Output LOW Voltage			0.5	V	I <sub>OL</sub> = 16 mA
I <sub>IN</sub>	Input Current			±200	μА	
C <sub>IN</sub>	Input Capacitance		4.0		pF	
C <sub>PD</sub>	Power Dissipation Capacitance		14		pF	Per Output
Z <sub>OUT</sub>	Output Impedance		12		Ω	
I <sub>CC</sub>	Maximum Quiescent Supply Current		0.5		mA	

# Table 3. AC Characteristics (T<sub>A</sub> = $0^{\circ}$ to $70^{\circ}$ C, V<sub>CCI</sub> = 2.5V $\pm 5\%$ , V<sub>CCO</sub> = 2.5V $\pm 5\%$ )

Symbol	Characteristic	Min	Тур	Max	Unit	Condition
F <sub>max</sub>	Maximum Frequency			200	MHz	
t <sub>PLH</sub>	Propagation Delay	1.5		2.8	ns	
t <sub>sk(o)</sub>	Output-to-Output Skew			200	ps	
t <sub>sk(pr)</sub>	Part-to-Part Skew			1.3	ns	Notes 1, 2
t <sub>sk(pr)</sub>	Part-to-Part Skew			600	ps	Notes 1, 3
d <sub>t</sub>	Duty Cycle	45		55	%	
t <sub>r</sub> , t <sub>f</sub>	Output Rise/Fall Time	0.2		1.0	ns	

# Table 4. DC Characteristics ( $T_A = 0^{\circ}$ to $70^{\circ}$ C, $V_{CCI} = 3.3$ V ±5%, $V_{CCO} = 3.3$ V ±5%)

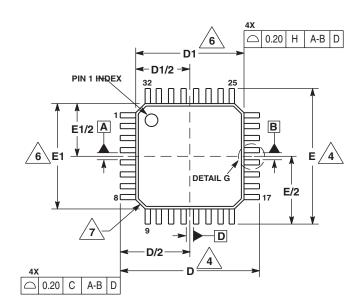
Symbol	Characteristic	Min	Тур	Max	Unit	Condition
V <sub>IH</sub>	Input HIGH Voltage	2.4		V <sub>CCI</sub>	V	
V <sub>IL</sub>	Input LOW Voltage			0.8	V	
V <sub>OH</sub>	Output HIGH Voltage	2.4			V	$I_{OH} = -20 \text{ mA}$
V <sub>OL</sub>	Output LOW Voltage			0.5	V	I <sub>OL</sub> = 20 mA
I <sub>IN</sub>	Input Current			±200	μА	
C <sub>IN</sub>	Input Capacitance		4.0		pF	
C <sub>PD</sub>	Power Dissipation Capacitance 14			pF	Per Output	
Z <sub>OUT</sub>	Output Impedance 12			Ω		
I <sub>CC</sub>	Maximum Quiescent Supply Current		0.5		mA	

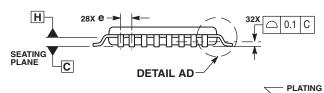
# Table 5. AC Characteristics ( $T_A = 0^{\circ}$ to $70^{\circ}$ C, $V_{CCI} = 3.3 V \pm 5\%$ , $V_{CCO} = 3.3 V \pm 5\%$ )

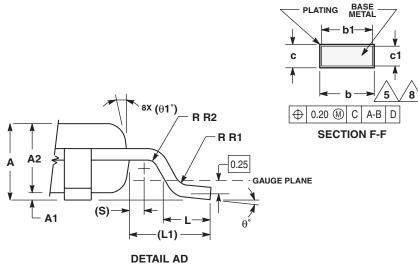
Symbol	Characteristic	Min	Тур	Max	Unit	Condition
F <sub>max</sub>	Maximum Frequency			250	MHz	
t <sub>PLH</sub>	Propagation Delay	1.3		2.3	ns	Note 1
t <sub>sk(o)</sub>	Output-to-Output Skew			200	ps	
t <sub>sk(pr)</sub>	Part-to-Part Skew			1.0	ns	Notes 1, 2
t <sub>sk(pr)</sub>	Part-to-Part Skew			500	ps	Notes 1, 3
d <sub>t</sub>	Duty Cycle	45		55	%	
t <sub>r</sub> , t <sub>f</sub>	Output Rise/Fall Time	0.2		1.0	ns	

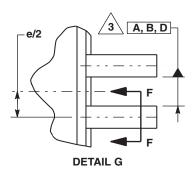
- 1. Tested using standard input levels, production tested @ 133 MHz.
- 2. Across temperature and voltage ranges, includes output skew.
- 3. For a specific temperature and voltage, includes output skew.

#### **PACKAGE DIMENSIONS**









- NOTES:
  1. DIMENSIONS ARE IN MILLIMETERS.
  2. INTERPRET DIMENSIONS AND TOLERANCES PER
  ASME Y14.5M, 1994.
  3. DATUMS A, B, AND D TO BE DETERMINED AT
  DATUM PLANE H.
  DIMENSIONS O AND F TO BE DETERMINED AT

- 3 DATUMS A, B, AND D TO BE DETERMINED AT
  DATUM PLANE H.
  4 DIMENSIONS D AND E TO BE DETERMINED AT
  SEATING PLANE C.
  5 DIMENSIONS D DOES NOT INCLUDE DAMBAR
  PROTRUSION. ALLOWABLE DAMBAR PROTRUSION
  SHALL NOT CAUSE THE LEAD WIDTH TO EXCEED
  THE MAXIMUM b DIMENSION BY MORE THAN
  0.08-mm. DAMBAR CANNOT BE LOCATED ON THE
  LOWER RADIUS OR THE FOOT. MINIMUM SPACE
  BETWEEN PROTRUSION AND ADJACENT LEAD OR
  PROTRUSION. 10.07-mm.
  6 DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD
  PROTRUSION. ALOWABLE PROTRUSION IS
  0.25-mm PER SIDE. D1 AND E1 ARE MAXIMUM
  PLASTIC BODY SIZE DIMENSIONS INCLUDING
  MOLD MISMATCH.
  2 REACT SHAPE OF EACH CORNER IS OPTIONAL.
  8 THESE DIMENSIONS APPLY TO THE FLAT
  SECTION OF THE LEAD BETWEEN 0.1-mm AND
  0.25-mm FROM THE LEAD TIP.

	MILLIMETERS			
DIM	MIN	MAX		
Α	1.40	1.60		
A1	0.05	0.15		
A2	1.35	1.45		
b	0.30	0.45		
b1	0.30	0.40		
С	0.09	0.20		
c1	0.09	0.16		
D	9.00 BSC			
D1	7.00	BSC		
е	0.80	BSC		
Е	9.00	BSC		
E1	7.00	BSC		
L	0.50	0.70		
L1	1.00			
q	0°	7°		
q1	12 REF			
R1	0.08	0.20		
R2	0.08			
S	0.20 REF			

**CASE 873A-03 ISSUE B** LQFP PLASTIC PACKAGE

# **Contact Information:**

www.IDT.com

#### Sales

800-345-7015 (inside USA) +408-284-8200 (outside USA) Fax: 408-284-2775 www.IDT.com/go/contactIDT

## **Technical Support**

netcom@idt.com +480-763-2056

#### **Corporate Headquarters**

Integrated Device Technology, Inc. 6024 Silver Creek Valley Road San Jose, CA 95138 United States 800-345-7015 (inside USA) +408-284-8200 (outside USA)



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